

Item	Description	Customer Part Number	Package	Reference	Qty	Manufacturer
1	TI WL1837 WiFi/BT Module	WL1837MODGI	13.4x13.3x2.0mm	U1	1	Jorjin
2	XOSC 3225 / 32.768KHZ / 1.8V / ±50ppm	7XZ3200005	3.2x2.5x1.0mm	OSC1	1	TXC
3	ANT / Chip / 2.4GHz & 5GHz	W3006	10.0x3.2x1.5mm	ANT1,ANT2	2	Pulse
4	Mini RF Header Receptacle	U.FL-R-SMT-1(10)	3.0x2.6x1.25mm	J5,J6	2	Hirose
5	IND 0402 / 1.3nH / ±0.1nH / SMD	LQP15MN1N3B02	0402	L1	1	Murata
6	IND 0402 / 1.8nH / ±0.1nH / SMD	LQP15MN1N8B02	0402	L3	1	Murata
7	IND 0402 / 2.2nH / ±0.1nH / SMD	LQP15MN2N2B02	0402	L4	1	Murata
8	CAP 0402 / 1pF / 50V / C0G / ±0.1pF	GJM1555C1H1R0BB01	0402	C13	1	Murata
9	CAP 0402 / 2.4pF / 50V / C0G / ±0.1pF	GJM1555C1H2R4BB01	0402	C14	1	Murata
10	CAP 0402 / 0.1uF / 10V / X7R / ±10%	0402B104K100CT	0402	C3,C4	2	Walsin
11	CAP 0402 / 1uF / 6.3V / X5R / ±10% / HF	GRM155R60J105KE19D	0402	C1	1	Murata
12	CAP 0603 / 10uF / 6.3V / X5R / ±20%	C1608X5R0J106M	0603	C2	1	TDK
13	RES 0402 / 0R / ±5%	WR04X000 PTL	0402	R1,R2,R3,R4,R6,R7,R8,R9,R10,R11,R12,R13,R14,R15,R16,R17,R18,R19,R21,R22,R23,R24,R25,R26,R27,R28,R29,R30,R33,C5,C6	31	Walsin
14	RES 0402 / 10K / ±5%	WR04X103 JTL	0402	R20	1	Walsin
15	RES 0603 / 0R / ±5%	WR06X000 PTL	0603	R31,R32	2	Walsin
16	PCB WG7837TEC8B D02 / Layer 4 / FR4 (4pcs/PNL)		76.0x31.0x1.6mm		1	茂榮

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